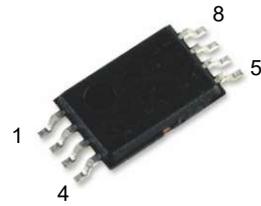


CMS2010-HF

N-Channel

RoHS Device

Halogen Free

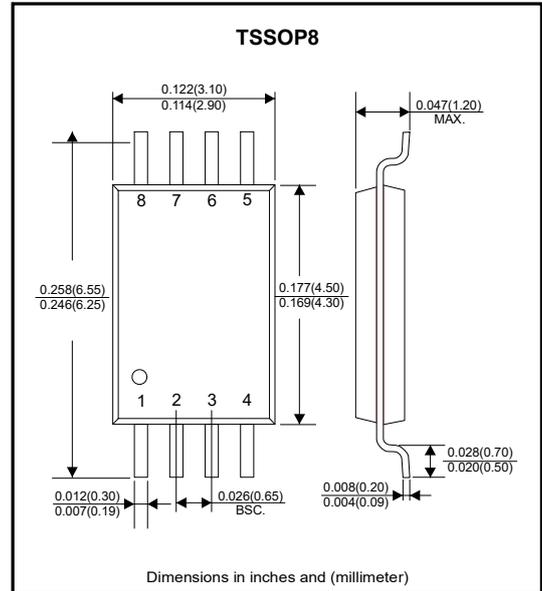


Features

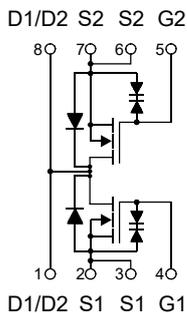
- $V_{DS} = 20V, I_D = 7A$
- $R_{DS(ON)} < 24m\Omega @ V_{GS}=2.5V$
- $R_{DS(ON)} < 18m\Omega @ V_{GS}=4.5V$
- ESD Rating: 2000V HBM
- High power and current handling capability
- Lead free product is acquired
- Surface mount package

Description

The NCE2010E uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 2.5V. This device is suitable for use as a load switch or in PWM applications. It is ESD protested.



Circuit diagram



Absolute Maximum Ratings (TA=25°C unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V_{DS}	20	V
Gate-Source Voltage	V_{GS}	± 12	V
Drain Current-Continuous	I_D	7	A
Drain Current-Pulsed ^(Note 1)	I_{DM}	30	A
Maximum Power Dissipation	P_D	1.5	W
Operating Junction and Storage Temperature Range	T_J, T_{STG}	-55 To 150	°C

Thermal Characteristic

Thermal Resistance, Junction-to-Ambient (Note 2)	$R_{\theta JA}$	83.3	°C/W
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Electrical Characteristics (TA=25°C unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{GS}=0V, I_D=250\mu A$	20	21.5	23	V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS}=20V, V_{GS}=0V$	-	-	1	μA
Gate-Body Leakage Current	I_{GSS}	$V_{GS}=\pm 10V, V_{DS}=0V$	-	-	± 10	μA
On Characteristics (Note 3)						
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=250\mu A$	0.5	0.7	0.9	V
Drain-Source On-State Resistance	$R_{DS(on)}$	$V_{GS}=4.5V, I_D=6.5A$	-	13	18	m Ω
		$V_{GS}=2.5V, I_D=5.5A$	-	17	24	m Ω
Forward Transconductance	g_{FS}	$V_{DS}=5V, I_D=7A$	-	20	-	S
Dynamic Characteristics (Note 4)						
Input Capacitance	C_{iss}	$V_{DS}=10V, V_{GS}=0V,$ $F=1.0MHz$	-	1150	-	PF
Output Capacitance	C_{oss}		-	185	-	PF
Reverse Transfer Capacitance	C_{rss}		-	145	-	PF
Switching Characteristics (Note 4)						
Turn-on Delay Time	$t_{d(on)}$	$V_{DD}=10V, R_L=1.35\Omega$ $V_{GS}=5V, R_{GEN}=3\Omega$	-	6		nS
Turn-on Rise Time	t_r		-	13		nS
Turn-Off Delay Time	$t_{d(off)}$		-	52		nS
Turn-Off Fall Time	t_f		-	16		nS
Total Gate Charge	Q_g	$V_{DS}=10V, I_D=7A,$ $V_{GS}=4.5V$	-	15		nC
Gate-Source Charge	Q_{gs}		-	0.8	-	nC
Gate-Drain Charge	Q_{gd}		-	3.2	-	nC
Drain-Source Diode Characteristics						
Diode Forward Voltage (Note 3)	V_{SD}	$V_{GS}=0V, I_S=1A$	-	-	1.2	V
Diode Forward Current (Note 2)	I_S		-	-	7	A

Notes:

1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board, $t \leq 10$ sec.
3. Pulse Test: Pulse Width $\leq 300\mu s$, Duty Cycle $\leq 2\%$.
4. Guaranteed by design, not subject to production

Typical Electrical and Thermal Characteristics

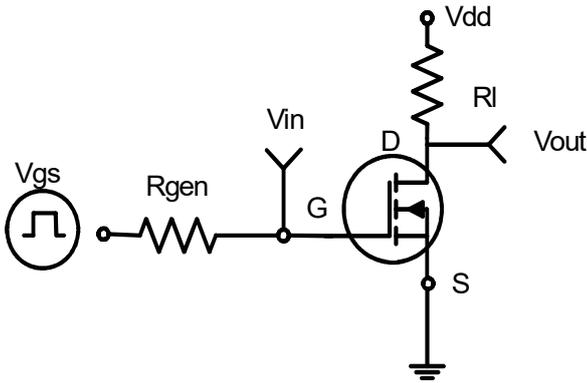


Figure 1: Switching Test Circuit

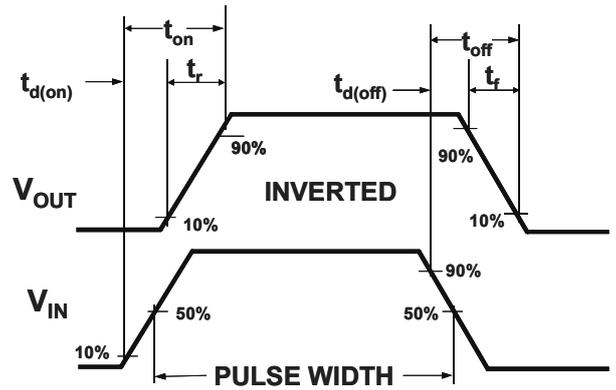


Figure 2: Switching Waveforms

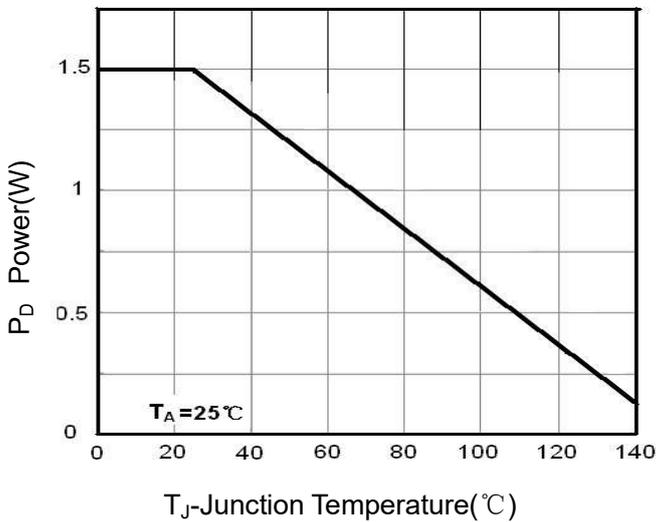


Figure 3 Power Dissipation

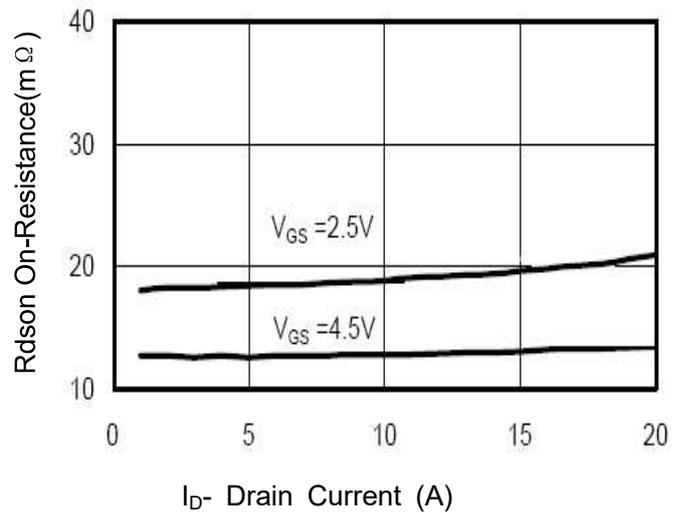


Figure 6 Drain-Source On-Resistance

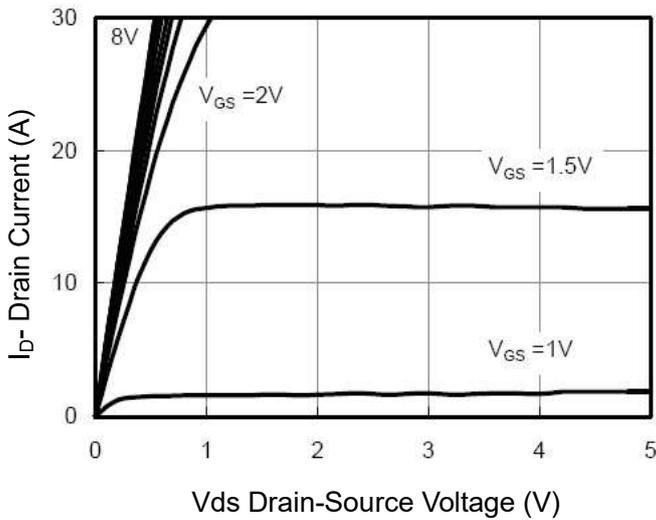


Figure 5 Output Characteristics

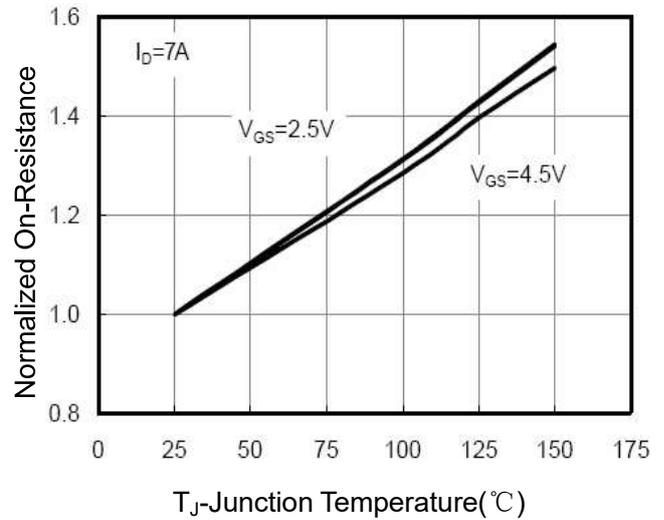
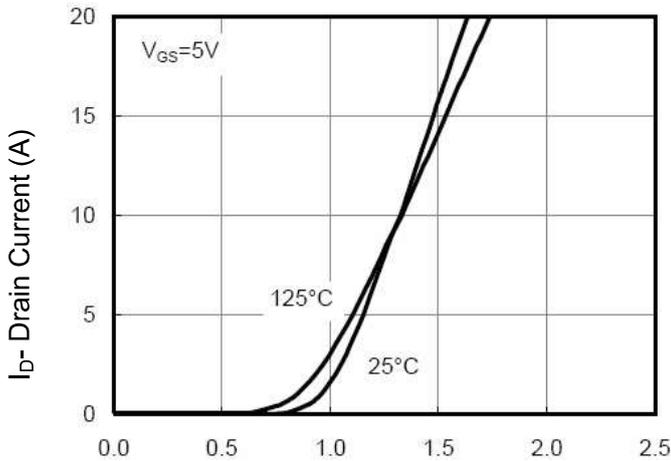
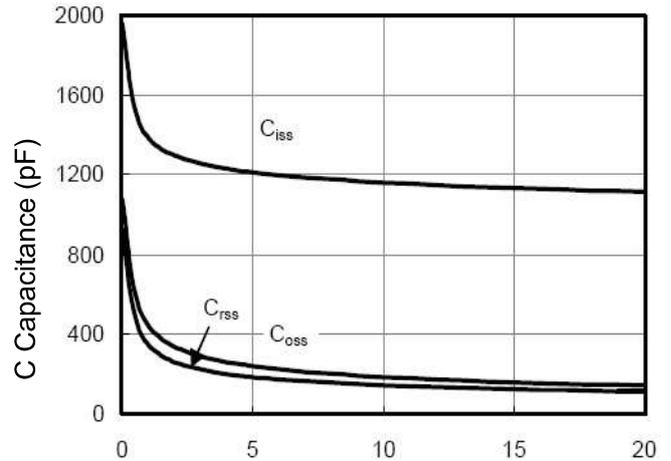


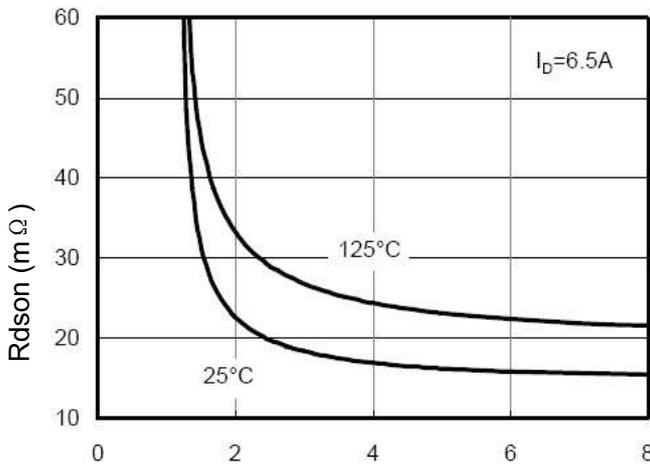
Figure 8 Drain-Source On-Resistance



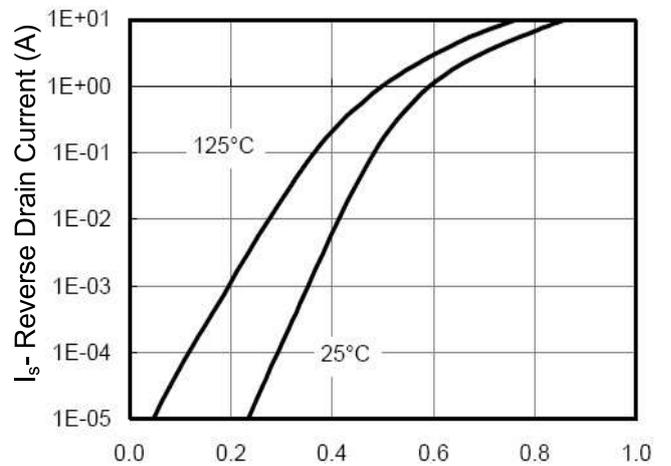
Vgs Gate-Source Voltage (V)
Figure 7 Transfer Characteristics



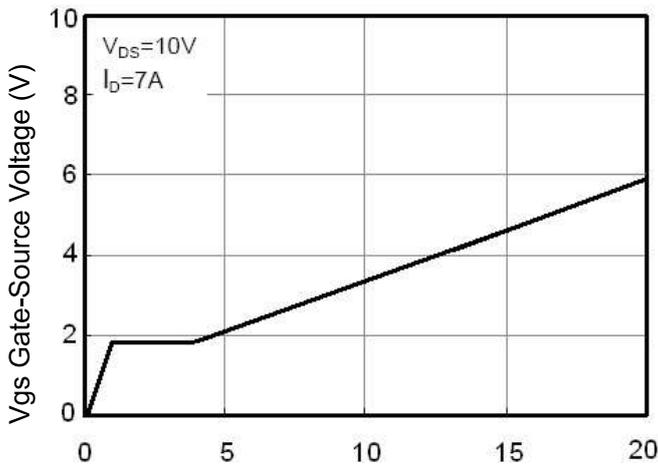
Vds Drain-Source Voltage (V)
Figure 8 Capacitance vs Vds



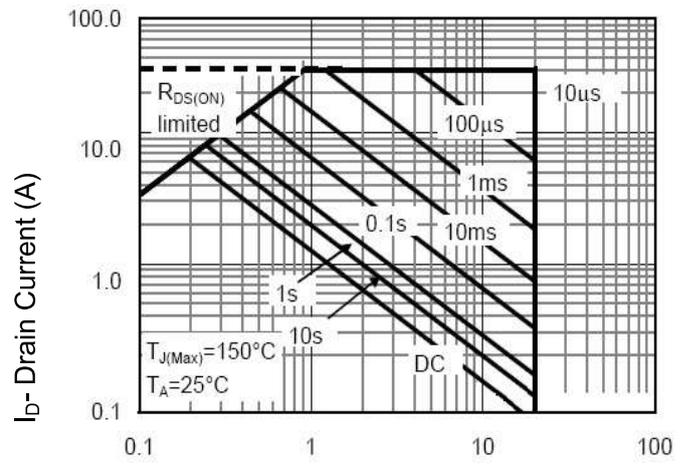
Vgs Gate-Source Voltage (V)
Figure 9 Rdson vs Vgs



Vds Drain-Source Voltage (V)
Figure 10 Capacitance vs Vds



Qg Gate Charge (nC)
Figure 11 Gate Charge



Vds Drain-Source Voltage (V)
Figure 13 Safe Operation Area

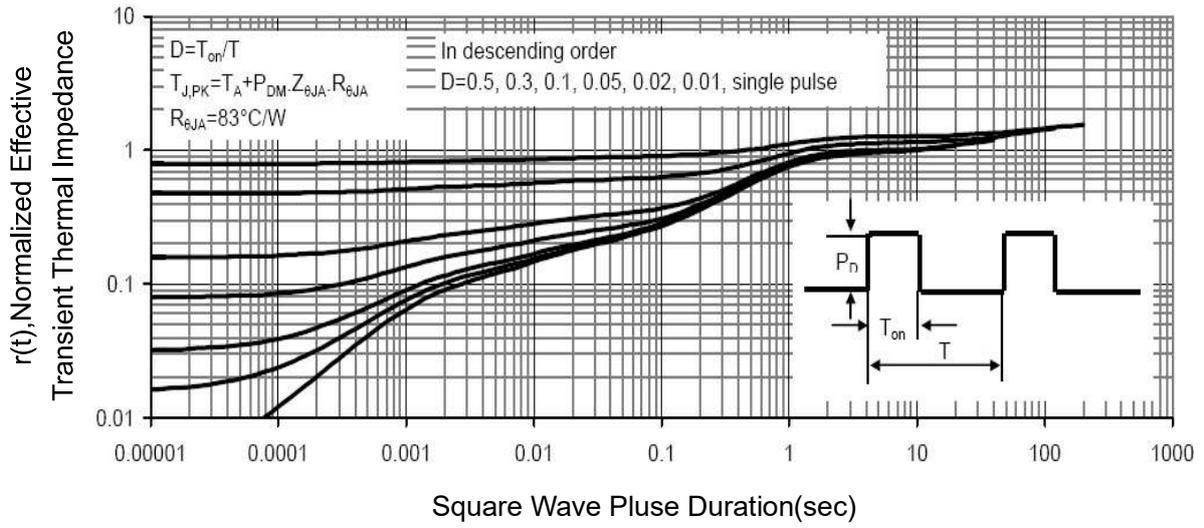
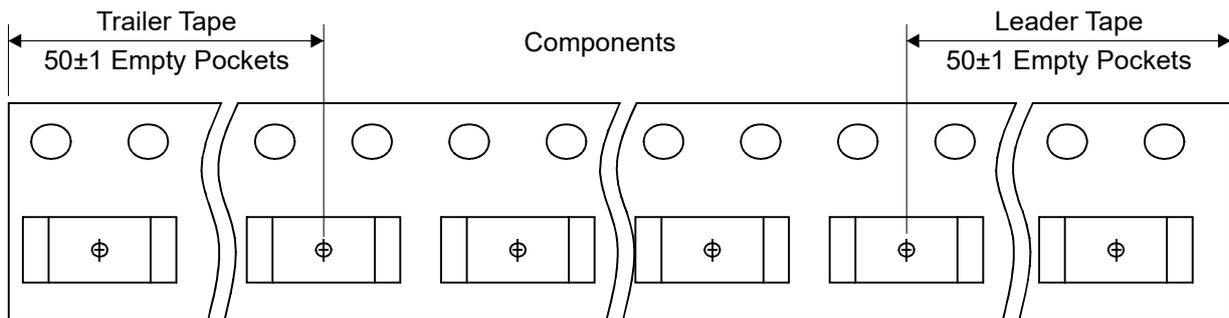
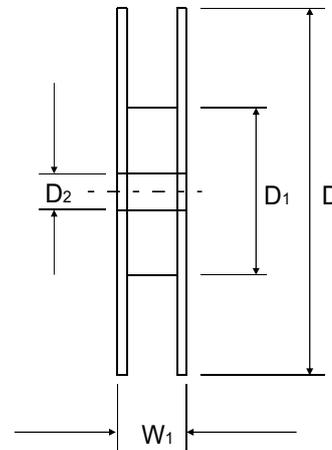
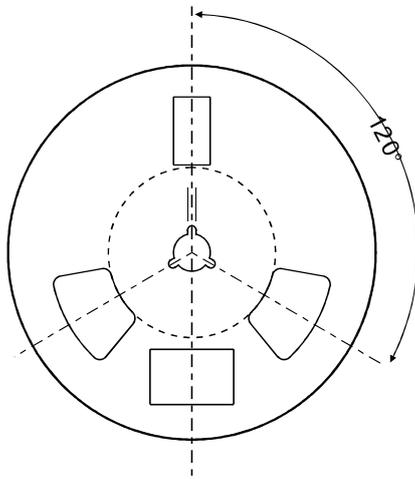
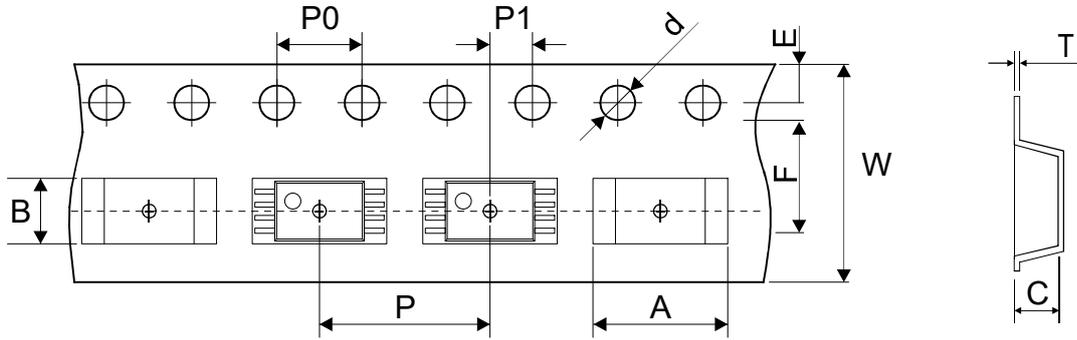


Figure 14 Normalized Maximum Transient Thermal Impedance

Reel Taping Specification



TSSOP8	SYMBOL	A	B	C	d	D	D1	D2
	(mm)	6.76 ± 0.10	3.30 ± 0.10	1.20 ± 0.10	1.50 ± 0.10	330 ± 1.00	100 ± 1.00	13.00 ± 1.00
	(inch)	0.266 ± 0.004	0.130 ± 0.004	0.047 ± 0.004	0.059 ± 0.004	13.00 ± 0.039	3.937 ± 0.039	0.512 ± 0.039

TSSOP8	SYMBOL	E	F	P	P0	P1	W	W1
	(mm)	1.75 ± 0.10	5.50 ± 0.10	8.00 ± 0.10	4.00 ± 0.10	2.00 ± 0.10	12.00 + 1.00 / - 0.10	17.60 ± 1.00
	(inch)	0.069 ± 0.004	0.217 ± 0.004	0.315 ± 0.004	0.157 ± 0.004	0.079 ± 0.004	0.472 + 0.039 / - 0.004	0.693 ± 0.039

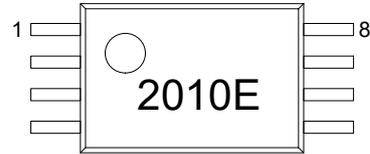
Company reserves the right to improve product design , functions and reliability without notice.

REV: A

CMS2010-HF

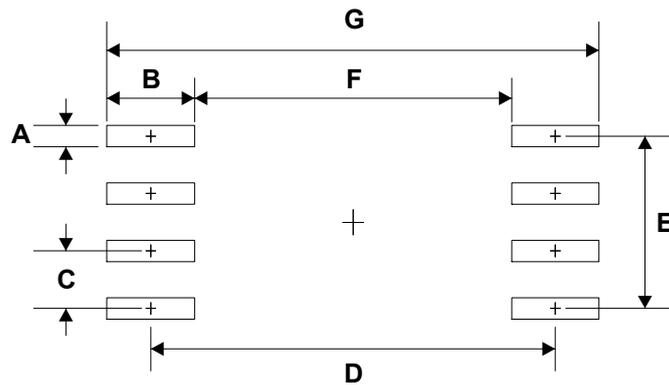
Marking Code

Part Number	Marking Code
CMS2010-HF	2010E



Suggested PAD Layout

SIZE	TSSOP8	
	(mm)	(inch)
A	0.32	0.013
B	1.60	0.063
C	0.65	0.026
D	5.60	0.220
E	1.95	0.077
F	4.00	0.157
G	7.20	0.283



Note:

- 1.General tolerance: $\pm 0.05\text{mm}$.
- 2.The pad layout is for reference purposes only.

Standard Packaging

Case Type	REEL PACK	
	REEL (pcs)	Reel Size (inch)
TSSOP8	3,000	13